## **AMPLEON**

## Package outline

OMP-780-6F-1 25.20 (18.01)(15.44)(2.15)8.85 1.00 (3) **7** 0.10(4) (0.75)R1.38 Α <del>Ф</del> 0.05 А  $\bigcirc$ (4.47) – (7.04) – (7.04)  $19.46 \pm 0.20$ 16.00 Ø2.00 0.1▼ R0.16 max. 0.10 2 -1.57 (5) <del>Ф</del> 0.25 В 3.85 (3) R1.00 **⊕** 0.05 B 3.92 <sup>+0.08</sup> <sub>-0.03</sub> 20.75(1)  $-0.22 \pm 0.05$ R0.32 В 20.57 (0.20) compound rim all around the perimeter of the heatsink 23.05 pin 7 (6) R0.60(4x) Min. 15.5 Min. 18.5 22.15 Tolerances unless otherwise stated: 0 Revision: Package outline drawing: 3/1/2018 Angle: ± 1° Dimension: ± 0.05 Revision date: units in mm. OMP-780-6F-1 Third angle projection Sheet 1 of 2



## Package outline

OMP-780-6F-1

Drawing Notes	
Items	Description
	Dimensions are excluding mold protrusion. Areas located adjacent to the leads have a maximum mold protrusion of 0.25
(1)	mm (per side) and 0.62 mm max. in length. In between the 14 leads the protrusion is 0.25 mm. max. At all other areas the
	mold protrusion is maximum 0.15 mm per side. See also detail B.
(2)	The metal protrusion (tie bars) in the corner will not stick out of the molding compound protrusions (detail A).
(3)	The lead dambar (metal) protrusions are not included. Add 0.14 mm max to the total lead dimension at the dambar location.
(4)	The lead coplanarity over all leads is 0.1 mm maximum.
(5)	Dimension is measured 0.5 mm from the edge of the top package body.
(6)	The hatched area indicates the exposed metal heatsink.
(7)	The leads and exposed heatsink are plated with matte Tin (Sn).

